

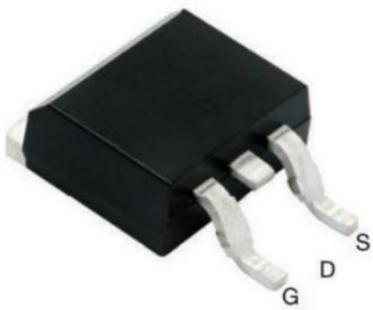
## Product Summary

- $V_{DS}$  -200 V
- $I_{DS}$  -15A
- $R_{DS(ON)}$  (at  $V_{GS} = -10V$ ) <290m $\Omega$  (Typ)

## Application

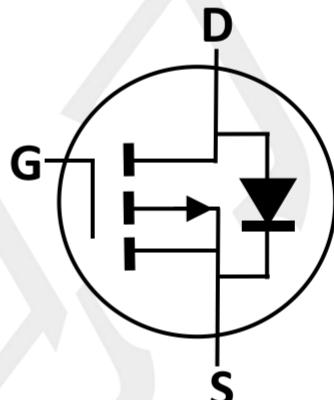
- Reverse Battery protection
- Load switch
- Power management
- PWM Application

## Package and Pin Configuration



TO-263

## Circuit diagram



Equivalent Circuit

## Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$ unless otherwise noted)

PARAMETER	SYMBOL	LIMIT	UNIT
Drain-Source Voltage	$V_{DS}$	-200	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current	$I_D$	-15	A
Pulsed Drain Current (note1)	$I_{DM}$	-36	A
Maximum Power Dissipation $T_C=25^\circ\text{C}$	$P_D$	100	W
Operating Junction Temperature Range	$T_J$	-55 to +150	$^\circ\text{C}$
Storage Temperature Range	$T_{stg}$	-55 to +150	$^\circ\text{C}$

## Thermal Characteristic

PARAMETER	Symbol	Value	Unit
Thermal Resistance from Junction to Case( $t \leq 10s$ )	$R_{\theta JC}$ (note2)	1.25	$^\circ\text{C}/\text{W}$

notes 1. Repetitive Rating: Pulse width limited by maximum junction temperature.

2 . When mounted on 1" square PCB (FR4 material).

**Electrical Characteristics** ( $T_A=25^\circ\text{C}$  unless otherwise noted)

PARAMETER	CONDITIONS	SYMBOL	MIN	TYP	MAX	UNIT
<b>Static</b>						
Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=-250\mu\text{A}$	$BV_{DSS}$	-200	--	--	V
Gate-Source Threshold Voltage	$V_{DS}=V_{GS}, I_D= -250\mu\text{A}$	$V_{GS(\text{th})}$	-2.0	-2.8	-4.0	V
Gate-Source Leakage	$V_{DS}=0V, V_{GS}= \pm 20V$	$I_{GSS}$	--	--	$\pm 100$	nA
Zero Gate Voltage Drain Current	$V_{DS}= -200V, V_{GS}=0V$	$I_{DSS}$	--	-0.1	-1	$\mu\text{A}$
	$V_{DS}= -200V, T_J=125^\circ\text{C}$		--	-10	-50	$\mu\text{A}$
Drain-Source On-State Resistance (Note 1)	$V_{GS}= -10V, I_D= -6A$	$R_{DS(\text{on})}$	--	290	330	$\text{m}\Omega$
Forward Transconductance (Note 2)	$V_{DS}= -10V, I_D= -6A$	$g_{fs}$	--	22	--	S
<b>Dynamic</b> (Note 2)						
Total Gate Charge (Note 3)	$V_{DS} = -100V,$ $I_D = -6A,$ $V_{GS} = -10V$	$Q_g$	--	56	--	nC
Gate-Source Charge (Note 3)		$Q_{gs}$	--	11	--	
Gate-Drain Charge (Note 3)		$Q_{gd}$	--	8.5	--	
Input Capacitance	$V_{DS} = -75V,$ $V_{GS} = 0V,$ $F= 1.0\text{MHz}$	$C_{iss}$	--	3600	--	pF
Output Capacitance		$C_{oss}$	--	455	--	
Reverse Transfer Capacitance		$C_{rss}$	--	186	--	
<b>Switching</b>						
Turn-On Delay Time (Note 3)	$V_{DD} = -100V,$ $I_D= -6A,$ $V_{GS} = -10V,$ $R_{GEN} = 6\Omega$	$t_{d(on)}$	--	33	--	nS
Rise Time (Note 3)		$t_r$	--	19	--	
Turn-Off Delay Time (Note 3)		$t_{d(off)}$	--	149	--	
Fall Time (Note 3)		$t_f$	--	50	--	
<b>Source-Drain Diode Ratings and Characteristics</b> (Note 2)						
Forward Voltage	$V_{GS} = 0V, I_{SD} = -1A$	$V_{SD}$	--	-0.76	-1.1	V
Continuous Source Current	Integral reverse diode in the MOSFET	$I_s$	--	--	-15	A
Pulsed Current (Note 1)		$I_{SM}$	--	--	-36	A

Notes:

1. Pulse test; pulse width  $\leq 300 \mu\text{s}$ , duty cycle  $\leq 2\%$ .
2. Guaranteed by design, not subject to production testing.
3. Independent of operating temperature

## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

Figure 1. Output Characteristics

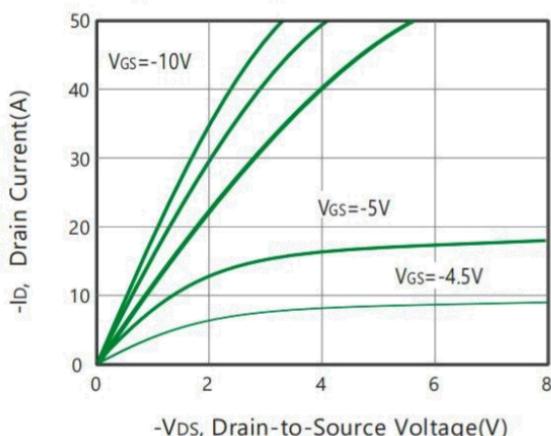


Figure 3. On-Resistance vs. Gate-Source Voltage

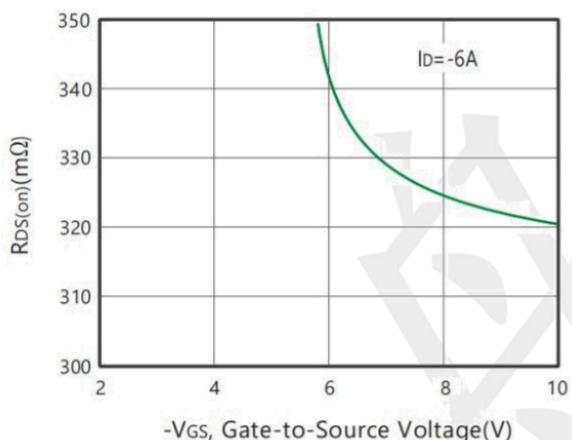


Figure 5. Gate Threshold Variation with Temperature

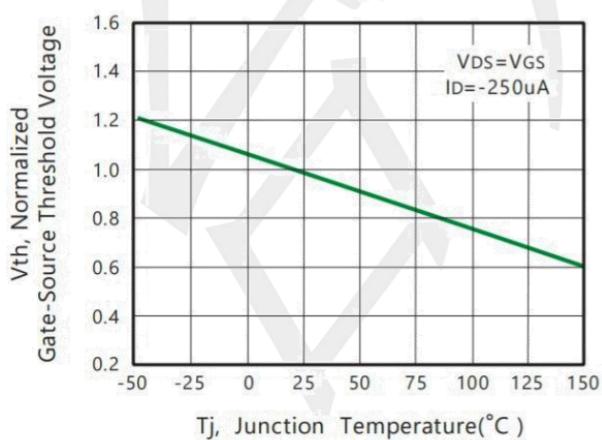


Figure 2. Body Diode Forward Voltage Variation with Source Current

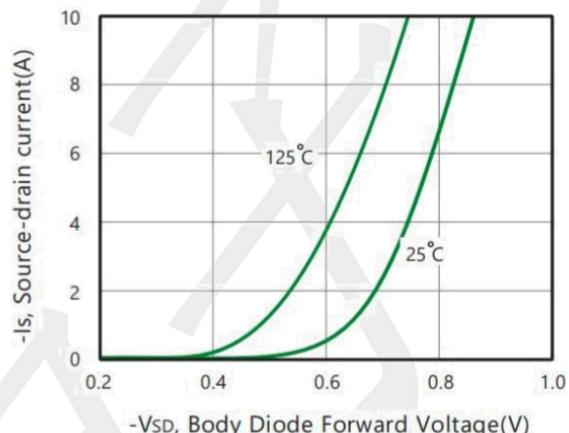


Figure 4. On-Resistance Variation with Drain Current and Temperature

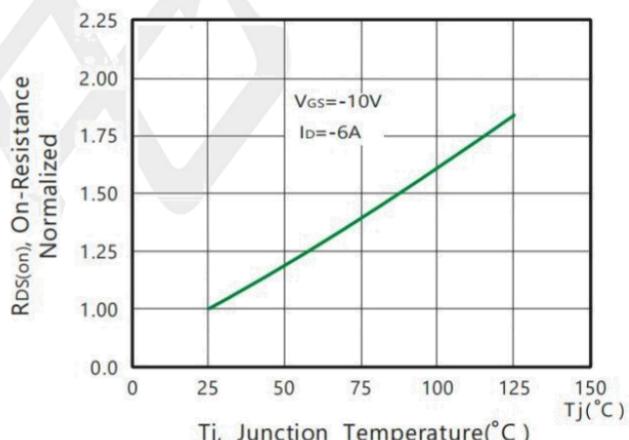
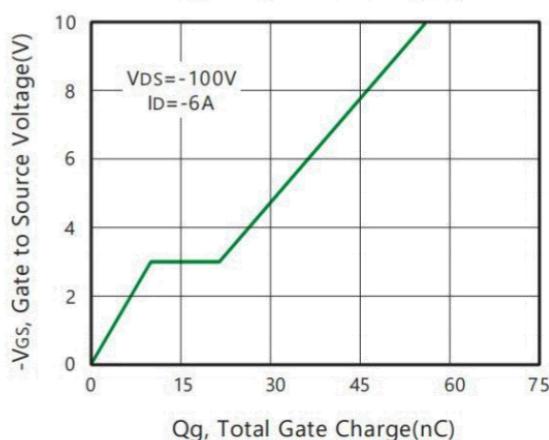
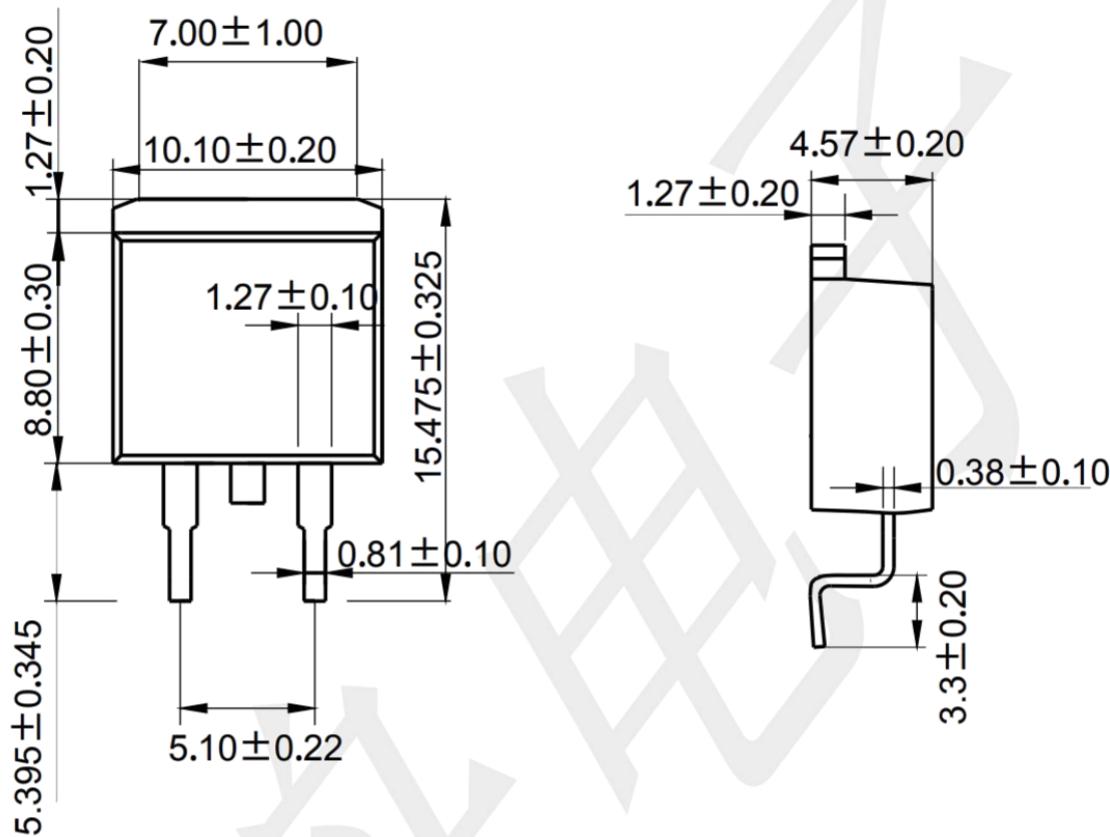


Figure 6. Gate Charge



### Package Outline Dimensions (unit: mm)

TO-263



### Mounting Pad Layout (unit: mm)

